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Microstructure, indentation and work hardening of Cu/Ag multilayers

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Abstract

Instrumented indentation and tensile tests were performed on free standing Cu/Ag multilayer thin films with layer thicknesses in the range 0.85–900 nm. The effect of layer thickness on the work hardening rate was investigated. The work hardening rate was found to increase with increasing layer thickness. The effect of layer thickness on the work hardening rate was found to increase with increasing layer thickness. The effect of layer thickness on the work hardening rate was found to increase with increasing layer thickness.

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